

BY TELEFAX TO: (703) 872-9311
EXPEDITED PROCEDURE
RESPONSE UNDER 37 CFR 1.116
EXAMINING GROUP: 1700
BOX AF

DOCKET NO.: 4029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al.

| Art Unit: 1722

SERIAL NO.: 09/705,237

| Confirmation No.: 4586

FILED: November 2, 2000

| EX.: Thukhanh T. Nguyen

FOR: Die Used for Resin-Sealing and
Molding an Electronic Component

*Do not
enter
TN 6/3/03*
MS AF
COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

May 30, 2003

RESPONSE TO THE FINAL OFFICE ACTION OF APRIL 1, 2003 INCLUDING
AN ATTACHED COVER SHEET WITH CERTIFICATE OF TELEFAX TRANSMISSION

Dear Sir:

This Response should receive expedited handling, as it is being
filed within two months after the date of the Final Action.

Please amend the above identified application as follows.

**(THIS AMENDMENT IS IN THE NEW REVISED AMENDMENT FORMAT, WITH
DELETED MATTER SHOWN BY STRIKETHROUGH AND ADDED MATTER SHOWN BY
UNDERLINING. A SEPARATE MARKED-UP VERSION IS THUS NOT REQUIRED).**